
**Površinsko nameščeni piezoelektrični elementi za regulacijo in izbiranje frekvence
- Standardne mere in priključni izvodi - 1. del: Mere plastičnih okrovov**

Surface mounted piezoelectric devices for frequency control and selection - Standard outline and terminal lead connections - Part 1 : Plastic moulded enclosure outlines

Oberflächenmontierbare piezoelektrische Bauteile zur Frequenzstabilisierung und - Selektion - Norm-Gehäusemaße und Anschlüsse -- Teil 1: Kunststoffgehäuse

Dispositifs piézoélectriques à montage en surface pour la commande et le choix de la fréquence - Encombrements normalisés et connexions des sorties - Partie 1: Encombrements des enveloppes en plastique moulées

<https://standards.iteh.ai/en/standards/sist/61837-1-2012/https://standards.iteh.ai/en/standards/sist/61837-1-2012/183cc409869d/sist-en-61837-1-2012>

Ta slovenski standard je istoveten z: EN 61837-1:2012

ICS:

31.140	Piezoelektrične in dielektrične naprave	Piezoelectric and dielectric devices
--------	---	--------------------------------------

SIST EN 61837-1:2012

en

iTeh STANDARD PREVIEW
(standards.iteh.ai)

SIST EN 61837-1:2012

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-df91-4a73-9d31-183cc409869d/sist-en-61837-1-2012>

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 61837-1

August 2012

ICS 31.140

Supersedes EN 61837-1:1999

English version

**Surface mounted piezoelectric devices for frequency control and selection -
Standard outlines and terminal lead connections -
Part 1: Plastic moulded enclosure outlines
(IEC 61837-1:2012)**

Dispositifs piézoélectriques à montage en surface pour la commande et le choix de la fréquence -
Encombrements normalisés et connexions des sorties -
Partie 1: Encombrements des enveloppes en plastique moulées
(CEI 61837-1:2012)

Oberflächenmontierbare piezoelektrische Bauteile zur Frequenzstabilisierung und -selektion -
Norm-Gehäusemaße und Anschlüsse -
Teil 1: Kunststoffgehäuse
(IEC 61837-1:2012)

ITEH STANDARD PREVIEW
(standards.iteh.ai)

SIST EN 61837-1:2012

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-d91-4a73-9d31-100000000000/61837-1-2012>

This European Standard was approved by CENELEC on 2012-05-25. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 49/930/CDV, future edition 2 of IEC 61837-1, prepared by IEC/TC 49 "Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61837-1:2012.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2013-02-25
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2015-05-25

This document supersedes EN 61837-1:1999.

EN 61837-1:2012 includes the following significant technical changes with respect to EN 61837-1:1999:

- one enclosure type (SIP-L5/01) has been deleted;
- configuration symbol of enclosures is currently consolidated into one as DCC (dual chip carrier).

This standard shall be read in conjunction with EN 61240:1997.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

[SIST EN 61837-1:2012](https://standards.iteh.ai/catalog/standards/sist/baa8c614-d91-4a73-9d31-183cc409869d/sist-en-61837-1-2012)

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-d91-4a73-9d31-183cc409869d/sist-en-61837-1-2012>

Endorsement notice

The text of the International Standard IEC 61837-1:2012 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61240	1994	Piezoelectric devices - Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection - General rules	EN 61240	1997

iTeh STANDARD PREVIEW (standards.iteh.ai)

[SIST EN 61837-1:2012](https://standards.iteh.ai/catalog/standards/sist/baa8c614-df91-4a73-9d31-183cc409869d/sist-en-61837-1-2012)

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-df91-4a73-9d31-183cc409869d/sist-en-61837-1-2012>

iTeh STANDARD PREVIEW
(standards.iteh.ai)

SIST EN 61837-1:2012

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-df91-4a73-9d31-183cc409869d/sist-en-61837-1-2012>



IEC 61837-1

Edition 2.0 2012-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Surface mounted piezoelectric devices for frequency control and selection –
Standard outlines and terminal lead connections –
Part 1: Plastic moulded enclosure outlines**

**Dispositifs piézoélectriques à montage en surface pour la commande et le choix
de la fréquence – Encombrements normalisés et connexions des sorties –
Partie 1: Encombrements des enveloppes en plastique moulées**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

PRICE CODE
CODE PRIX

S

ICS 31.140

ISBN 978-2-8322-0078-0

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD	3
1 Scope	5
2 Normative references	5
3 Configuration of enclosures	5
4 Designation of types	5
5 Plastic moulded enclosure dimensions	6
6 Lead connections	6
7 Plastic moulded enclosures	6
Table 1 – Designation of plastic moulded enclosures	6

iTeh STANDARD PREVIEW
(standards.iteh.ai)

SIST EN 61837-1:2012

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-df91-4a73-9d31-183cc409869d/sist-en-61837-1-2012>

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SURFACE MOUNTED PIEZOELECTRIC DEVICES
FOR FREQUENCY CONTROL AND SELECTION –
STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –**

Part 1: Plastic moulded enclosure outlines

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61837-1 has been prepared by IEC technical committee 49: Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection.

This second edition cancels and replaces the first edition published in 1999. It is a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- one enclosure type (SIP-L5/01) has been deleted;
- Configuration symbol of enclosures is currently consolidated into one as DCC (dual chip carrier).

The text of this standard is based on the following documents:

CDV	Report on voting
49/930/CDV	49/969/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This International Standard shall be read in conjunction with IEC 61240:1994. IEC 61240:1994 deals with standard outlines and terminal lead connections as they apply to SMDs for frequency control and selection in plastic moulded enclosures.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61837 series, published under the general title *Surface mounted piezoelectric devices for frequency control and selection – Standard outlines and terminal lead connections*, can be found on the IEC web site.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[SIST EN 61837-1:2012](#)

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-d91-4a73-9d31-183cc409869d/sist-en-61837-1-2012>

SURFACE MOUNTED PIEZOELECTRIC DEVICES FOR FREQUENCY CONTROL AND SELECTION – STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –

Part 1: Plastic moulded enclosure outlines

1 Scope

This part of IEC 61837 deals with standard outlines and terminal lead connections as they apply to SMDs for frequency control and selection in plastic moulded enclosures and is based on IEC 61240.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61240: 1994, *Piezoelectric devices – Preparation of outline drawings of surface-mounted devices (SMD), for frequency control and selection – General rules*¹

3 Configuration of enclosures

SIST EN 61837-1:2012

<https://standards.iteh.ai/catalog/standards/sist/baa8c614-df91-4a73-9d31-185cc407804a/sist-en-61837-1-2012>

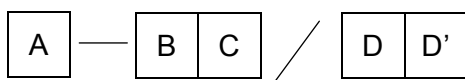
These enclosures are made of plastic moulded materials with the terminal leads based on the descriptive designation system for semiconductors, devices package.

The configuration symbols are shown as follows:

- DCC (dual chip carrier)

4 Designation of types

The designation of types is shown in four parts as follows:



A: Configuration symbol of enclosures:

- DCC (dual chip carrier);

B: Structure of terminal leads:

- J: leaded type;

C: Number of terminal leads

D: Two digit serial number

¹ A new edition is under consideration.